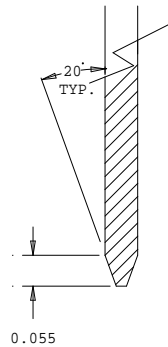
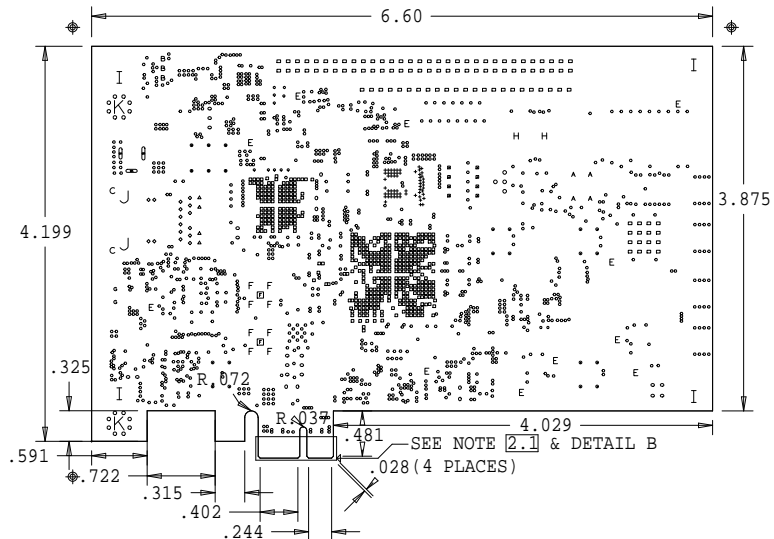


REVISIONS			
REV	DESCRIPTION	DATE	APPROVAL
A	INITIAL RELEASE	JUN-2013	
B	COMPONENT CHANGES	AUG-2013	
C	FEW COMPONENTS REMOVED	SEP-2013	
D	EDGE SMA AND SILK UPDATED	JAN-2014	



DETAIL B (EDGE BEVEL)

SCALE = NONE



PACTRON	
DATE: JAN 2014	
PROJECT NAME: M2GL_M2S-EVAL-KIT	REV: D
FILM LAYER: FAB	

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
*	8.0	+3.0/-8.0	PLATED	62
o	10.0	+3.0/-3.0	PLATED	503
*	10.0	+3.0/-3.0	PLATED	1224
*	25.0	+3.0/-3.0	PLATED	12
*	31.0	+3.0/-3.0	PLATED	8
o	35.0	+3.0/-3.0	PLATED	16
*	35.0	+5.0/-0.0	PLATED	16
*	39.0	+3.0/-3.0	PLATED	16
o	40.0	+3.0/-3.0	PLATED	4
o	40.0	+3.0/-3.0	PLATED	103
o	40.0	+3.0/-3.0	PLATED	17
o	40.0	+3.0/-3.0	PLATED	7
*	40.0	+5.0/-0.0	PLATED	4
A	45.0	+3.0/-3.0	PLATED	4
B	49.2126	+3.0/-3.0	PLATED	3
B	59.0551	+3.0/-3.0	PLATED	2
C	62.0	+3.0/-3.0	PLATED	2
F	62.9921	+3.0/-3.0	PLATED	8
E	65.0	+3.0/-3.0	PLATED	11
*	65.0	+4.0/-0.0	PLATED	6
G	35.5	+2.0/-0.0	NON-PLATED	2
H	66.0	+2.0/-0.0	NON-PLATED	2
I	125.0	+2.0/-2.0	NON-PLATED	4
K	125.0	+2.0/-2.0	NON-PLATED	2
J	128.0	+2.0/-2.0	NON-PLATED	2
8	118.1102x31.4961	+3.0/-3.0	PLATED	1
∞	118.1102x31.4961	+3.0/-3.0	PLATED	1
8	137.7953x31.4961	+3.0/-3.0	PLATED	1

NOTES: UNLESS OTHERWISE SPECIFIED

1. MATERIAL: 370 HR
2. BOARD TO BE SOLDER MASK OVER BARE COPPER, TOP AND BOTTOM LAYERS FULL BODY ELECTROPLATED GOLD REQUIRED 250 uINCHES Ni AND 3-5 uINCHES Au.

2.1. SELECTIVE HARD GOLD PLATING TO BE FLAT & PLATED 50-100uIN of Au OVER 150-200uIN of Ni. GOLD PLATING ON PAD SHOULD BE THE SAME LEVEL OR ABOVE THE SOLDER RESIST SURFACE ON TOP AND BOTTOM.
3. HOLES TO BE PLATED THROUGH.
PLATING IN HOLES TO BE 0.001 MIN. THICK.
4. HOLE SIZES ARE AFTER PLATING.
5. SILKSCREEN BOTH SIDES, WHITE.
6. FABRICATE PER DIMENSIONS SHOWN.
7. SOLDER MASK TOP AND BOTTOM SIDES WITH LIQUID PHOTO IMAGABLE OR DRY FILM SOLDER MASK. COLOR GREEN.
8. TOTAL BOARD THICKNESS: .63 mil+/- .5%
08 LAYER CONSTRUCTION. REFR STACKUP
9. APPLY THIEVING AS REQUIRED.
10. WRAP OR TWIST SHOULD NOT EXCEED .005" PER INCH
11. BOARD MUST BE UL 94V-1 APPROVED, AND ROHS COMPLIANT.
12. FABRICATE BOARD PER IPC-A-600D STANDARD.
CLIP SILKSCREEN ON NO MASK AREA.
14. IMPEDANCE TOLERANCE SHOULD BE +/- 10%.
15. NO VENDOR LOGO, ART WORKS SHOULD NOT BE CHANGED WITHOUT PRIOR APPROVAL FROM PACTRON
16. DEBURR ALL SHARP EDGES
17. REMOVE UNUSED PADS IN ALL INNER LAYER
18. BOARD DIMENSIONS ARE IN INCHES
19. EDGE FINGER- CHAMFER EDGES MUST BE FREE OF CUTTING BURRS.

STACKUP: 8 LAYERS

CONTROLLED IMPEDANCE REQUIRED

		TOP SIDE SOLDER MASK (0.4-0.8 MIL)	50 OHM SINGLE	100 OHM DIFFERENTIAL	90 OHM DIFFERENTIAL
		COPPER THICKNESS-0.5oz			
		PLATING THICKNESS-0.8 MIL			
		TOP (1.4 mil)			
	FR-4	DIELECTRIC (3.2 mil)	5.0 MILS	4.5/7.5 MILS	4.4 / 7.6 mils
		GND#2 (0.65 mil)			
	FR-4	DIELECTRIC (4 mil)			
		SIG#3 (1.3 mil)			
	FR-4	DIELECTRIC (15 mil)	5.0 MILS	4.0/7.0 MILS	
		PWR#4 (0.65 mil)			
	FR-4	DIELECTRIC (8 mil)			
		PWR#5 (0.65 mil)			
	FR-4	DIELECTRIC (15 mil)			
		SIG#6 (1.3 mil)			
	FR-4	DIELECTRIC (4 mil)	5.0 MILS	4.0/7.0 MILS	
		GND#7 (0.65 mil)			
	FR-4	DIELECTRIC (3.2 mil)			
		BOTTOM (1.4 mil)			
		PLATING THICKNESS-0.8 MIL	5.0 MILS	4.5/7.5 MILS	4.4 / 7.6 mils
		COPPER THICKNESS-0.5oz			
		BOTTOM SIDE SOLDER MASK (0.4-0.8 MIL)			

TOTAL THICKNESS: 63 mil+/- 5 %

NOTE: DIELECTRIC GLASS STYLE SHOULD NOT BE CHANGED WITHOUT PRIOR APPROVAL FROM PACTRON.

PACTRON

3000 PATRICK HENRY DRIVE, SANTA CLARA, CA 95054.
408-329-5500(PHONE), 408-747-1239(FAX).

PROJECT NAME	M2GL_M2S-EVAL-KIT Rev D	
PART NUMBER	DVP-102-000402-001	REV : D
DATE	JAN 2014	
PACTRON PART NUMBER	305-PD-13-1205	